

FXMAR2104 Dual-Supply, 4-Bit Voltage Translator / Isolator for Open-Drain and Push-Pull Applications

Features

SEMICONDUCTOR

- Bi-Directional Interface between Any Two Levels: 1.65V to 5.5V
- Direction Control Not Needed
- Internal 10KΩ Pull-Up Resistors
- System GPIO Resources Not Required when OE Tied to V_{CCA}
- I²C-Bus[®] Isolation
- A/B Port V_{OL} = 175mV (Typical), V_{IL} = 150mV, I_{OL} = 6mA
- Open-Drain Inputs / Outputs
- Works in a Push-Pull Environment
- Accommodates Standard-Mode and Fast-Mode I²C-Bus Devices
- Supports I²C Clock Stretching & Multi-Master
- Fully Configurable: Inputs and Outputs Track V_{CC}
- Non-Preferential Power-Up; Either V_{CC} May Be Powered-Up First
- Outputs Switch to 3-State if Either V_{CC} is at GND
- Tolerant Output Enable: 5V
- Packaged in 12-Lead Ultrathin MLP (1.8mm x 1.8mm)
- ESD Protection Exceeds:
 5kV HBM (per JESD22-A114)
 - 2kV CDM (per JESD22-C101)

Description

The FXMAR2104 is a 4-bit high-performance, configurable dual-voltage supply, open-drain translator for bi-directional voltage translation over a wide range of input and output voltages levels. The FXMAR2104 also works in a push-pull environment.

Intended for use as a voltage translator in applications using the $l^2C\text{-Bus}^\circledast$ interface, the input and output voltage levels are compatible with l^2C device specification voltage levels. Eight internal $10K\Omega$ pull-up resistors are integrated.

The device is designed so that the A port tracks the V_{CCA} level and the B port tracks the V_{CCB} level. This allows for bi-directional A/B port voltage translation between any two levels from 1.65V to 5.5V. V_{CCA} can equal V_{CCB} from 1.65V to 5.5V.

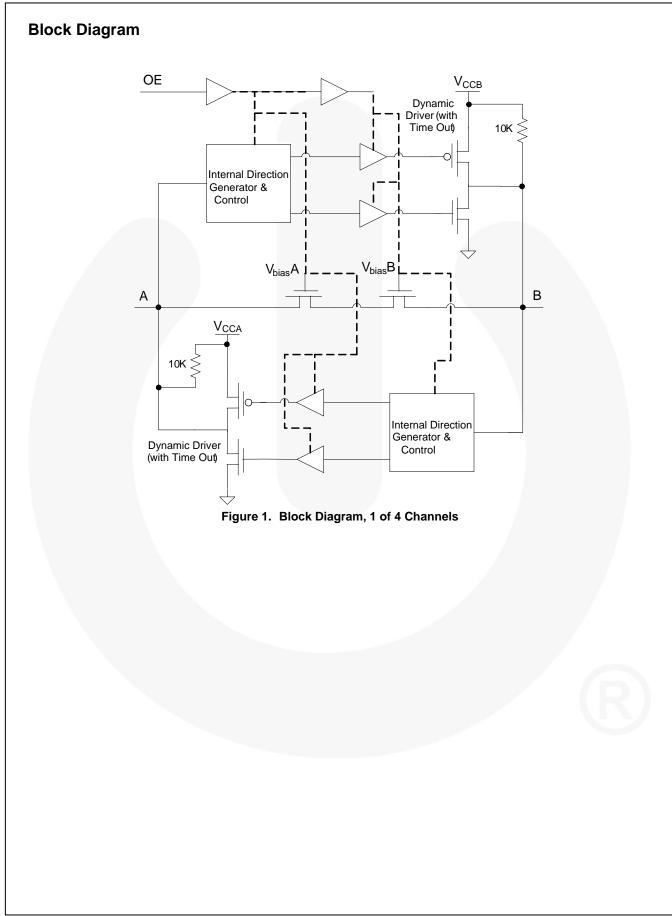
Non-preferential power-up means V_{CC} can be poweredup first. Internal power-down control circuits place the device in 3-state if either V_{CC} is removed.

The two ports of the device have automatic directionsense capability. Either port may sense an input signal and transfer it as an output signal to the other port.

Ordering Information

Part Number	mper i e i					
FXMAR2104UMX	-40 to +85°C	BY	12-Lead, Ultrathin MLP, 1.8mm x 1.8mm	5000 Units on Tape and Reel		

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Pin Configuration

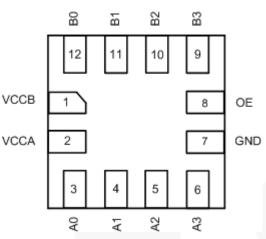


Figure 2. UMLP (Top-Through View)

Pin Definitions

Pin #	Name	Description
1	V _{CCB}	B-Side Power Supply
2	V _{CCA}	A-Side Power Supply
3, 4, 5, 6	A ₀ , A _{1,} A ₂ , A ₃	A-Side Inputs or 3-State Outputs
7	GND	Ground
8	OE	Output Enable Input
9, 10, 11, 12	B ₃ , B ₂ , B ₁ , B ₀	B-Side Inputs or 3-State Outputs

Truth Table

Control	Outputs			
OE	Outputs			
LOW Logic Level	3-State			
HIGH Logic Level	Normal Operation			

Note:

 If the OE pin is driven LOW, the FXMAR2104 is disabled and the A₀, A₁, A₂, A₃, B₀, B₁, B₂ and B₃ pins (including dynamic drivers) are forced into 3-state. Also, if the OE pin is driven LOW, all eight 10KΩ internal pull-up resistors are decoupled from their respective V_{CC}s. FXMAR2104 — Dual-Supply, 4-Bit Voltage Translator / Isolator / for Open-Drain and Push-Pull Applications

Absolute Maximum Ratings

Stresses exceeding the Absolute Maximum Ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol		Parameter	Min.	Max.	Unit			
V_{CCA}, V_{CCB}	Supply Voltage		-0.5	7.0				
V _{IN}		A Port	-0.5	7.0	V			
	DC Input Voltage	B Port	-0.5	7.0	v			
		Control Input (OE)	-0.5	7.0				
		An Outputs 3-State	-0.5	7.0				
V	$O_{\rm utput}$ $(a) taga (2)$	B _n Outputs 3-State	-0.5	7.0	V			
Vo	Output Voltage ⁽²⁾	An Outputs Active	-0.5	$V_{CCA} + 0.5V$	V			
		B _n Outputs Active	-0.5	V _{CCB} + 0.5V				
I _{IK}	DC Input Diode Current	At V _{IN} < 0V		-50	mA			
I _{OK}	DC Output Diada Current	At $V_0 < 0V$		-50	mA			
IOK	DC Output Diode Current	At $V_0 > V_{CC}$	$\begin{array}{c ccccc} -0.5 & 7.0 \\ -0.5 & 7.0 \\ -0.5 & 7.0 \\ -0.5 & 7.0 \\ -0.5 & 7.0 \\ -0.5 & 7.0 \\ -0.5 & V_{CCA} + 0.5 \\ -0.5 & V_{CCB} + 0.5 \\ -0.5 & V_{CCB} + 0.5 \\ -0.5 & -50 \\ -50 & +50 \\ -50 & +50 \\ -50 & \pm 100 \\ 0.129 \\ -65 & \pm 150 \\ 8 \\ 8 \\ 5 \\ \end{array}$	mA				
I _{OH} / I _{OL}	DC Output Source/Sink Cur	rent	$\begin{array}{c cccc} -0.5 & 7.0 \\ -0.5 & 7.0 \\ -0.5 & 7.0 \\ -0.5 & 7.0 \\ -0.5 & 7.0 \\ -0.5 & 7.0 \\ -0.5 & 7.0 \\ -0.5 & 7.0 \\ -0.5 & V_{CCA} + 0.5 \\ -0.5 & V_{CCB} + 0.5 \\ -0.5 & V_{CCB} + 0.5 \\ -0.5 & -50 \\ -50 & +50 \\ -50 & +50 \\ -50 & +50 \\ -50 & \pm 100 \\ 0.129 \\ -65 & \pm 150 \\ 8 \\ 8 \\ 5 \\ \end{array}$	mA				
Icc	DC V _{CC} or Ground Current p		±100	mA				
PD	Power Dissipation	At 400KHz		0.129	mW			
T _{STG}	Storage Temperature Range	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	+150	°C				
		-	8					
ESD	Electrostatic Discharge Capability	-		5	kV			
I _{CC} P _D T _{STG}		Charged Device Mode, JESD22-C101		2				

Note:

2. I_0 absolute maximum rating must be observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol		Parameter	Min.	Max.	Units
V_{CCA}, V_{CCB}	Power Supply Operating		1.65	5.50	V
	Input Voltage	A Port	0	5.5	
V _{IN}		B Port	0	5.5	V
		Control Input (OE)	0	V _{CCA}	
Θ_{JA}	Thermal Resistance	hermal Resistance			C°/W
T _A	Free Air Operating Temper	ee Air Operating Temperature			°C

Note:

3. All unused I/O pins should be disconnected.

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Functional Description

Application Circuit

Power-Up/Power-Down Sequencing

FXM translators offer an advantage in that either V_{CC} may be powered up first. This benefit derives from the chip design. When either V_{CC} is at 0V, outputs are in a high-impedance state. The control input (OE) is designed to track the V_{CCA} supply. A pull-down resistor tying OE to GND should be used to ensure that bus contention, excessive currents, or oscillations do not occur during power-up/power-down. The size of the pull-down resistor is based upon the current-sinking capability of the device driving the OE pin.

The recommended power-up sequence is:

1. Apply power to the first V_{CC} .

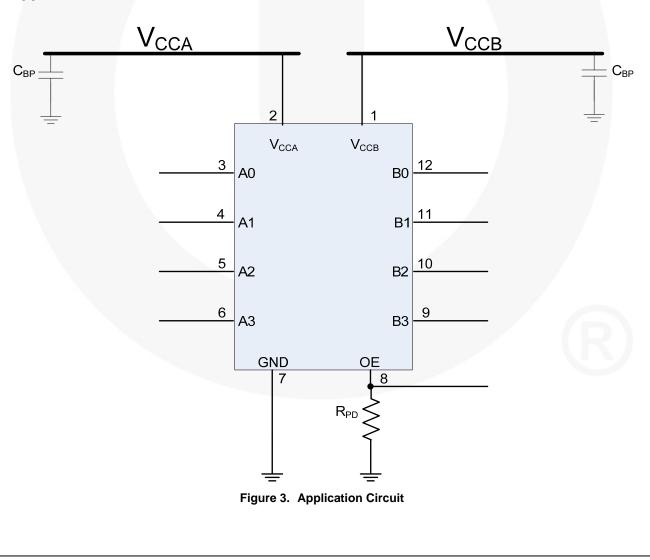
- 2. Apply power to the second V_{CC}.
- 3. Drive the OE input HIGH to enable the device.

The recommended power-down sequence is:

- 1. Drive OE input LOW to disable the device.
- 2. Remove power from either V_{CC} .
- 3. Remove power from other V_{CC} .

Note:

4. Alternatively, the OE pin can be hardwired to V_{CCA} to save GPIO pins. If OE is hardwired to V_{CCA} , either V_{CC} can be powered up or down first.



Application Information

The FXMAR2104 has four bi-directional, open-drain I/Os and includes a total of eight internal 10K · pull-up resistors (RPUs) on each port of all four data I/O pins. If a pair of data I/O pins (An/Bn) is not used, these pins should be left unconnected, eliminating unwanted current flow through the internal RPUs. External RPUs can be added to the I/Os to reduce the total RPU value, depending on the total bus capacitance. The user is free to lower the total pull-up resistor value to meet the maximum I²C edge rate per the I²C specification (UM10204 rev. 03, June 19, 2007). For example, according to the I²C specification, the maximum edge rate (30% - 70%) during Fast Mode (400kbit/s) is 300ns. If the bus capacitance is approaching the maximum 400pF, a lower total RPU value helps keep the rise time below 300ns (Fast Mode). Likewise, the I²C specification also specifies a minimum SCL high time of 600ns during Fast Mode (400KHz). Lowering the total RPU also helps increase the SCL high time. If the bus capacitance approaches 400pF, consider the FXMA2102, which does not contain internal RPUs. Then the user can calculate the ideal external RPU value. Section 7.1 of the I²C specification provides an excellent guideline for pull-up resistor sizing.

Theory of Operation

The FXMAR2104 is designed for high-performance level shifting and buffer / repeating in an I^2C application. Figure 1 shows that each bi-directional channel contains two series-Npassgates and two dynamic drivers. This hybrid architecture is highly beneficial in an I^2C application where auto-direction is a necessity.

For example, during the following three I^2C protocol events:

- Clock Stretching
- Slave's ACK Bit (9th bit = 0) following a Master's Write Bit (8th bit = 0)
- Clock Synchronization and Multi Master Arbitration

the bus direction needs to change from master-to-slave to slave to master without the occurrence of an edge. If there is an I^2C translator between the master and slave in these examples, the I^2C translator must change direction when both A and B ports are LOW. The Npassgates can accomplish this task very efficiently because, when both A and B ports are LOW, the Npassgates act as a low resistive short between the two (A and B) ports.

Due to I^2C 's open-drain topology, I^2C masters and slaves are not push-pull drivers. Logic LOWs are "pulled down" (I_{sink}), while logic HIGHs are "let go" (3-state). For example, when the master lets go of SCL (SCL always

comes from the master), the rise time of SCL is largely determined by the RC time constant, where $R = R_{PU}$ and C = the bus capacitance. If the FXMAR2104 is attached to the master [on the A port] and there is a slave on the B port, the Npassgates act as a low resistive short between the ports until either of the port's V_{CC}/2 thresholds are reached. After the RC time constant has reached the V_{CC}/2 threshold of either port, the port's edge detector triggers both dynamic drivers to drive their respective ports in the LOW-to-HIGH (LH) direction, accelerating the rising edge. The resulting rise time resembles the scope shot in Figure 4. Effectively, two distinct slew rates appear in rise time. The first slew rate (slower) is the RC time constant of the bus. The second slew rate (much faster) is the dynamic driver accelerating the edge.

If both the A and B ports of the translator are HIGH, a high-impedance path exists between the A and B ports because both the Npassgates are turned off. If a master or slave device decides to pull SCL or SDA LOW, that device's driver pulls down (I_{sink}) SCL or SDA until the edge reaches the A or B port V_{CC}/2 threshold. When either the A or B port threshold is reached, the port's edge detector triggers both dynamic drivers to drive their respective ports in the HIGH-to-LOW (HL) direction, accelerating the falling edge.

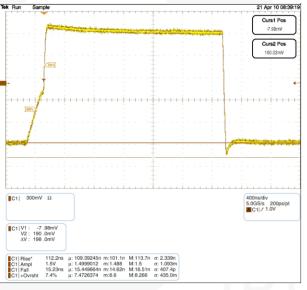


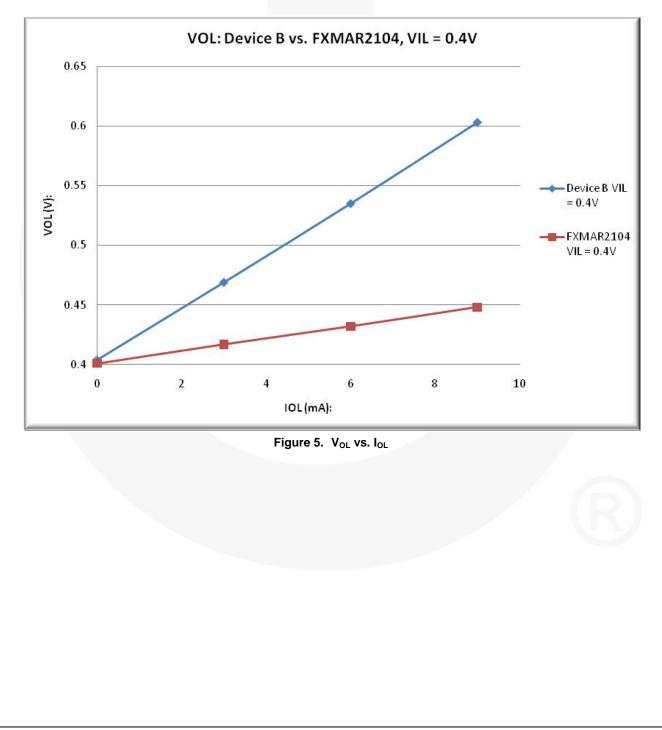
Figure 4. Waveform C: 600pF, Total R_{PU}: 2.2KΩ

V_{OL} vs. I_{OL}

The l^2C specification mandates a maximum V_{lL} (I_{OL} of 3mA) of $V_{CC} \bullet 0.3$ and a maximum V_{OL} of 0.4V. If there is a master on the A port of an l^2C translator with a V_{CC} of 1.65V and a slave on the l^2C translator B port with a V_{CC} of 3.3V, the maximum V_{lL} of the master is (1.65V x 0.3) 495mV. The slave could legally transmit a valid logic LOW of 0.4V to the master.

If the I²C translator's channel resistance is too high, the voltage drop across the translator could present a V_{IL} to

the master greater than 495mV. To complicate matters, the l^2C specification states that 6mA of l_{OL} is recommended for bus capacitances approaching 400pF. More l_{OL} increases the voltage drop across the l^2C translator. The l^2C application benefits when l^2C translators exhibit low V_{OL} performance. Figure 5 depicts typical FXMAR2104 V_{OL} performance vs. a competitor, given a 0.4V V_{IL} .



I²C Bus Isolation

The FXMAR2104 supports I^2C -Bus[®] isolation for the following conditions:

- Bus isolation if bus clear
- Bus isolation if either V_{CC} goes to ground

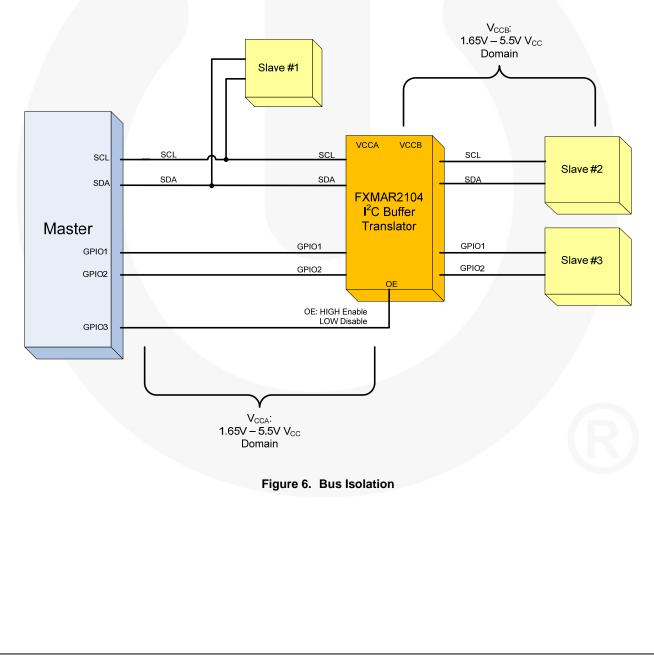
Bus Clear

Because the I^2C specification defines the minimum SCL frequency of DC, the SCL signal can be held LOW forever; however, this condition shuts down the I^2C bus. The I^2C specification refers to this condition as Bus Clear. In Figure 6, if slave #2 holds down SCL forever, the master and slave #1 are not able to communicate because the FXMAR2104 passes the SCL stuck-LOW condition from slave #2 to slave #1 as well as the

master. However, if the OE pin is pulled LOW (disabled), both ports (A and B) are 3-stated. This results in the FXMAR2104 isolating slave #2 from the master and slave #1, allowing full communication between the master and slave #1.

Either V_{CC} to GND

If slave #2 is a camera that is suddenly removed from the I^2C bus, resulting in V_{CCB} transitioning from a valid V_{CC} (1.65V - 5.5V) to 0V; the FXMAR2104 automatically forces all I/Os on both its A and B ports into 3-state. Once V_{CCB} has reached 0V, full I^2C communication between the master and slave #1 remains undisturbed.



DC Electrical Characteristics

$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$).
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Symbol	Parameter		Condition	V _{CCA} (V)	V _{CCB} (V)	Min.	Тур.	Max.	Unit
V	High Level Input	Data	Inputs A _n	1.65-5.50	1.65-5.50	$V_{CCA} - 0.4$			v
V _{IHA}	Voltage A	Cont	rol Input OE	1.65-5.50	1.65-5.50	$0.7 \text{ x V}_{\text{CCA}}$			V
V_{IHB}	High Level Input Voltage B	Data	Inputs B _n	1.65-5.50	1.65-5.50	$V_{CCB} - 0.4$			V
	Low Level Input	Data	Inputs A _n	1.65-5.50	1.65-5.50			0.4	
V _{ILA}	Voltage A	Cont	rol Input OE	1.65-5.50	1.65-5.50			0.3 x V _{CCA}	V
V_{ILB}	Low Level Input Voltage B	Data	Inputs B _n	1.65-5.50	1.65-5.50			0.4	V
		V _{IL} =	0.15V						
Vol	Low Level Output Voltage	I _{OL} =	6mA	1.65-5.50	1.65-5.50			0.4	V
١L	Input Leakage Current		rol Input OE, V _{CCA} or GND	1.65-5.50	1.65-5.50			±1	μA
	Power-Off Leakage Current	An	V_{IN} or $V_O = 0V$ to 5.5V	0	5.50			±2	
I _{OFF}		Bn	V_{IN} or $V_O = 0V$ to 5.5V	5.50	0			±2	μA
		A _n , B _n	$V_0 = 0V$ to 5.5V, OE = V _{IL}	5.50	5.50			±2	
I _{OZ}	3-State Output Leakage ⁽⁶⁾	An	$V_0 = 0V$ to 5.5V, OE = Don't Care	5.50	0			±2	μΑ
		Bn	$V_0 = 0V$ to 5.5V, OE = Don't Care	0	5.50			±2	
I _{CCA} / _B	Quiescent Supply Current ^(7,8)		V _{CCI} or ing, I _O = 0	1.65-5.50	1.65-5.50			5	μA
I _{CCZ}	Quiescent Supply Current ⁽⁷⁾	V _{IN} = I _O = (V_{CCI} or GND, 0, OE = V_{IL}	1.65-5.50	1.65-5.50			5	μA
	Quiescent	V _{IN} =	5.5V or GND,	0	1.65-5.50			-2	
I _{CCA}	Supply Current ⁽⁶⁾	been $I_0 = 0, OE = Don't$ V Current ⁽⁶⁾ $I_0 = 0, OE = Don't$ Care, B_n to A_n 1.65-5.50 0	0			2	μA		
	Quiescent		5.5V or GND, Io	1.65-5.50	0			-2	
I _{CCB}	Supply Current ⁽⁶⁾		DE = Don't , A _n to B _n	0	1.65-5.50			2	μA
R _{PU}	Resistor Pull-up Value	V _{CCA}	& V _{CCB} Sides	1.65-5.50	1.65-5.50		10		KΩ

5. This table contains the output voltage for static conditions. Dynamic drive specifications are given in the Dynamic Output Electrical Characteristics.

6. "Don't Care" indicates any valid logic level.

7. V_{CCI} is the V_{CC} associated with the input side.

8. Reflects current per supply, V_{CCA} or V_{CCB} .

Dynamic Output Electrical Characteristics

Output Rise / Fall Time

Output load: $C_L = 50pF$, $R_{PU} = NC$, push-pull driver, and $T_A = -40^{\circ}C$ to $+85^{\circ}C$.

		V _{cco} ⁽¹⁰⁾					
Symbol	Parameter	4.5 to 5.5V 3.0 to 3.6V 2.3 to 2.7V		1.65 to 1.95V	Unit		
		Typical					
t _{rise}	Output Rise Time; A Port, B Port ⁽¹¹⁾	3	4	5	7	ns	
t _{fall}	Output Fall Time; A Port, B Port ⁽¹²⁾	11	8	6	4	ns	

Notes:

9. Output rise and fall times guaranteed by design simulation and characterization; not production tested.

10. V_{CCO} is the V_{CC} associated with the output side.

11. See Figure 11.

12. See Figure 12.

Maximum Data Rate⁽¹³⁾

Output load: $C_L = 50 pF$, $R_{PU} = NC$, push-pull driver, and $T_A = -40^{\circ}C$ to $+85^{\circ}C$.

			Vo	ССВ		
V _{CCA}	Direction	4.5 to 5.5V	3.0 to 3.6V	2.3 to 2.7V	1.65 to 1.95V	Unit
4.5V to 5.5V	A to B	26	20	16	9	MHz
4.50 10 5.50	B to A	26	20	16	9	
3.0V to 3.6V	A to B	26	20	16	9	MHz
3.00 10 3.60	B to A	26	20	16	9	
2.3V to 2.7V	A to B	26	20	16	9	
2.30 10 2.70	B to A	26	20	16	9	MHz
1.65\/ to 1.05\/	A to B	26	20	16	9	
1.65V to 1.95V	B to A	26	20	16	9	MHz

Note:

13. F-toggle guaranteed by design simulation; not production tested.

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AC Characteristics⁽¹⁷⁾

		V _{ссв}								
Symbol	Parameter	4.5 to	o 5.5V	3.0 to	o 3.6V	2.3 to	o 2.7V	1.65 to	o 1.95V	Uni
		Тур.	Max.	Тур.	Max.	Тур.	Max.	Тур.	Max.	I
$V_{CCA} = 4.5$	5 to 5.5V				•			•		
	A to B	1	3	1	3	1	3	1	3	ns
	B to A	1	3	2	4	3	5	4	7	
4	A to B	2	4	3	5	4	6	6	7	
tozi	B to A	2	4	2	5	2	6	5	7	ns
tozi	OE to A	4	5	6	10	5	9	7	15	
τ _{PZL}	OE to B	3	5	4	7	5	8	10	15	ns
	OE to A	65	100	65	105	65	105	65	105	
t _{PLZ}	OE to B	5	9	6	10	7	12	9	16	ns
t _{skew}	A Port, B Port ⁽¹⁴⁾	0.5	1.5	0.5	1.0	0.5	1.0	0.5	1.0	ns
$V_{CCA} = 3.0$								1		
1	A to B	2.0	5.0	1.5	3.0	1.5	3.0	1.5	3.0	
t _{PLH}	B to A	1.5	3.0	1.5	4.0	2.0	6.0	3.0	9.0	ns
tou	A to B	2.0	4.0	2.0	4.0	2.0	5.0	6.0	7.0	
t _{PHL}	B to A	2.0	4.0	2.0	4.0	2.0	5.0	3.0	5.0	ns
t _{PZL}	OE to A	4.0	8.0	5.0	9.0	6.0	11.0	7.0	15.0	-
t _{PZL}	OE to B	4.0	8.0	6.0	9.0	8.0	11.0	10.0	14.0	ns
t _{PLZ}	OE to A	100	115	100	115	100	115	100	115	ns
	OE to B	5	10	4	8	5	10	9	15	
t _{skew}	A Port, B Port ⁽¹⁴⁾	0.5	1.5	0.5	1.0	0.5	1.0	0.5	1.0	ns
$V_{CCA} = 2.3$		0.0	1.0	0.0	1.0	0.0	1.0	0.0	1.0	110
	A to B	2.5	5.0	2.5	5.0	2.0	4.0	1.0	3.0	
t _{PLH}	B to A	1.5	3.0	2.0	4.0	3.0	6.0	5.0	10.0	ns
	A to B	2	5	2.0	5	2	5	5		-
t _{PHL}	B to A	2	5	2	5	2	5	3	6 6	ns
	OE to A	5.0	10.0	5.0	10.0	6.0	12.0	90.0	18.0	-
t _{PZL}	OE to B	4.0	8.0	4.5	9.0	5.0	10.0	90.0	18.0	ns
							115			
t _{PLZ}	OE to A OE to B	100	115	100	115	100		100	115	ns
	A Port, B Port ⁽¹⁴⁾	65	110 1.5	65	110	65	115	12 0.5	25 1.0	
t _{skew}	65 to 1.95V	0.5	1.5	0.5	1.0	0.5	1.0	0.5	1.0	ns
$\mathbf{v}_{\text{CCA}} = 1.\mathbf{c}$		1.0	7.0	4.0	7.0	5.0	0.0	5.0	10.0	
t _{PLH}	A to B	4.0	7.0	4.0	7.0	5.0	8.0	5.0	10.0	ns
	B to A	1.0	2.0	1.0	2.0	1.5	3.0	5.0	10.0	-
t _{PHL}	A to B	5	8	3	7	3	7	8	9	ns
	B to A	4	8	3	7	3	7	3	7	1
t _{PZL}	OE to A	11	15	11	14	14	28	14	23	ns
	OE to B	6	14	6	14	6	14	9	19	-
t _{PLZ}	OE to A	75	115	75	115	75	115	75	115	ns
	OE to B	75	115	75	115	75	115	75	115	
t _{skew}	A Port, B Port ⁽¹⁴⁾	0.5	1.5	0.5	1.0	0.5	1.0	0.5	1.0	ns

Note:

14. Skew is the variation of propagation delay between output signals and applies only to output signals on the same port (A_n or B_n) and switching with the same polarity (LOW-to-HIGH or HIGH-to-LOW) (see Figure 14). Skew is guaranteed, but not tested.

15. AC Characteristic is guaranteed by Design and Characterization

Capacitance

$T_A = +25^{\circ}C.$

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance Control Pin (OE)	$V_{CCA} = V_{CCB} = GND$	2.2	pF
C _{I/O}	Input/Output Capacitance, An, Bn	$V_{CCA} = V_{CCB} = 5.0V, OE = GND$	13.0	pF

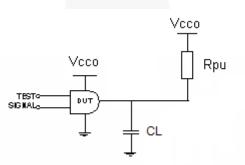


Figure 7. AC Test Circuit

Table 1. Propagation Delay Table⁽¹⁶⁾

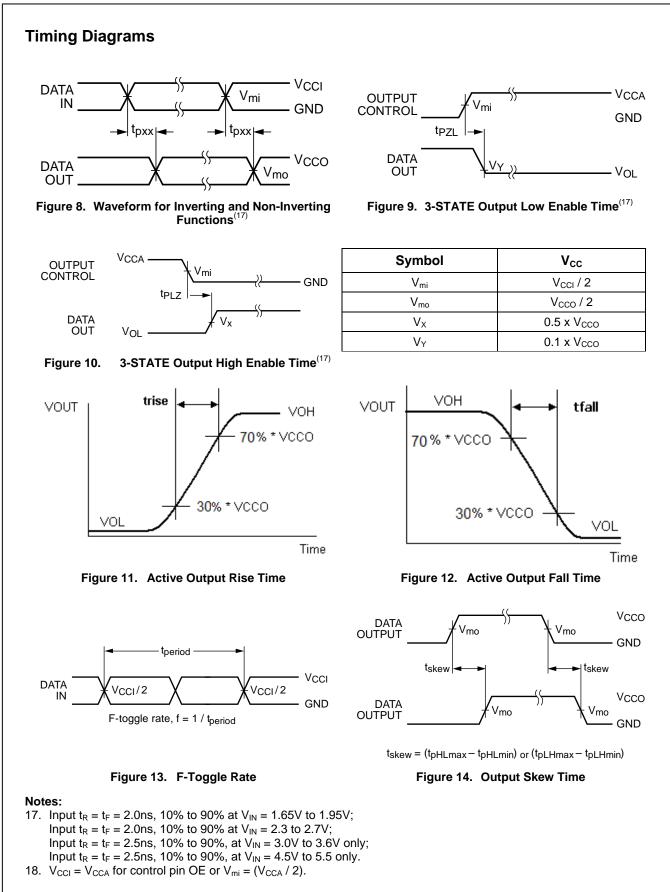
Test	Input Signal	Output Enable Control
t _{PLH} , t _{PHL}	Data Pulses	Vcca
t _{PZL} (OE to A _n , B _n)	0V	LOW to HIGH Switch
t _{PLZ} (OE to A _n , B _n)	0V	HIGH to LOW Switch

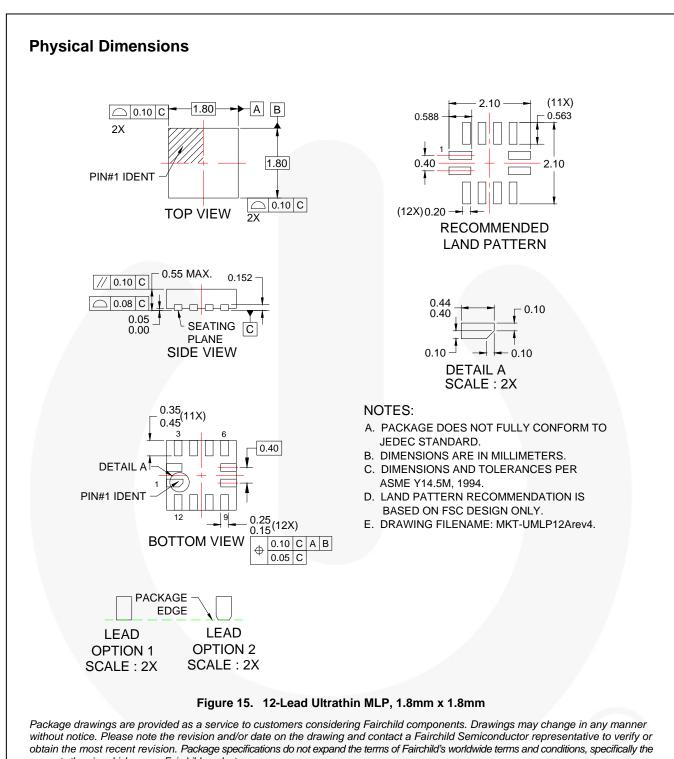
Note:

16. For t_{PZL} and t_{PLZ} testing, an external 2.2K Ω pull-up resistor to V_{CCO} is required to force the I/O pins HIGH while OE is LOW. When OE is low, the internal 10K Ω RPUs are decoupled from their respective V_{CC} 's.

Table 2. AC Load Table

V _{cco}	CL	RL
1.8 ± 0.15V	50pF	NC
2.5 ± 0.2V	50pF	NC
3.3 ± 0.3V	50pF	NC
5.0 ± 0.5V	50pF	NC





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